

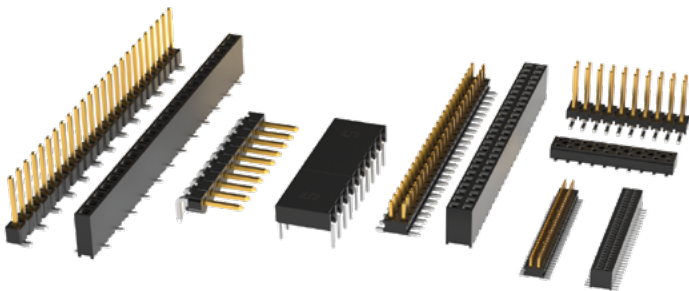
FLEXIBLE SIGNAL INTEGRITY SOLUTIONS

Samtec offers many board stacker solutions rated up to 8 Gbps and compatible with many popular industry standards, including PCIe® Gen 1 through 3, JTAG, LVDS, and others. These products provide cost-effective solutions to run high-speed signals in a variety of applications.

With the industry's largest variety of board-to-board interconnects, and the most design flexibility to solve almost every design challenge, Samtec makes it easy to find the right board stacking solution.



Design Flexibility



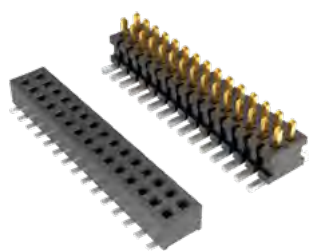
- Pitches: 1.27 mm, 2.00 mm & 2.54 mm
- Total number of I/Os: 4 - 200
- Number of rows: 1 - 4
- Post height adjustable in .005" increments
- Body positions adjustable in .005" increments
- Supports stack heights from 4.8 mm to 29.4 mm
- Multiple plating options available
- Multiple orientations & terminations available
- Rugged options such as screw downs and latches

Modified Solutions



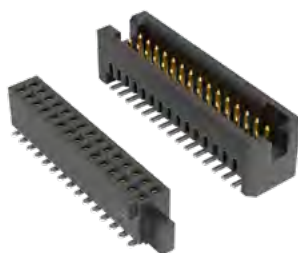
- Ability to move the body anywhere on the pin
- Stack height flexibility
- Application specific plating options
- Pin removal to aid in keying
- Ability to bend pins to meet any angle
- Extremely low and often no MOQs
- Customer specific labeling
- Print and sample for express modifications
- Flexible packaging options

Flexible Solutions Up To 8 Gbps



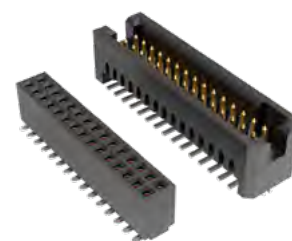
FTSH / CLP

Pitch: 1.27 mm
 Total number of I/Os: 4 - 100
 Stack Height: 4.8 - 5.2 mm
 Orientations: P, PE, H
 Terminations: T/H, SMT & MT



SFM / TFM

Pitch: 1.27 mm
 Total number of I/Os: 6 - 100
 Stack Height: 6 - 11.8 mm
 Orientations: P, PE, H
 Terminations: T/H & SMT



SFMC / TFM

Pitch: 1.27 mm
 Total number of I/Os: 4 - 100
 Stack Height: 5.9 - 11.6 mm
 Orientations: P, PE
 Terminations: T/H & SMT



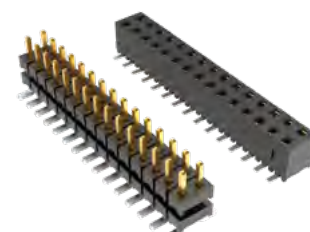
FOLC / MOLC

Pitch: 1.27 mm
 Total number of I/Os: 80 - 200
 Stack Height: 6, 7.75, 11.4 mm
 Orientations: P
 Terminations: T/H, SMT & MT



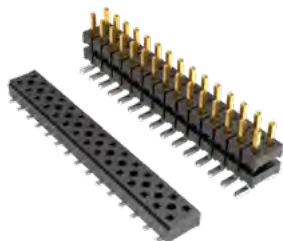
S2M / T2M

Pitch: 2.00 mm
 Total number of I/Os: 10 - 60
 Stack Height: 6.2, 7.06 mm
 Orientations: P, PE
 Terminations: T/H & SMT



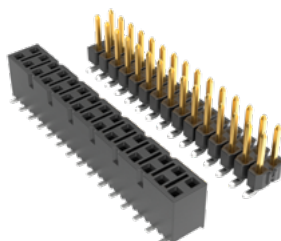
MMS / TW

Pitch: 2.00 mm
 Total number of I/Os: 4 - 100
 Stack Height: 7.5 - 29.4 mm
 Orientations: P, PE
 Terminations: T/H & SMT



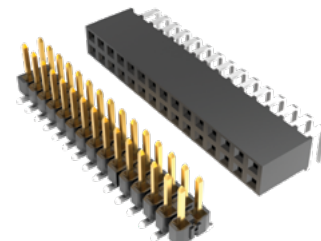
CLT / TW

Pitch: 2.00 mm
 Total number of I/Os: 4 - 100
 Stack Height: 5.2 - 27 mm
 Orientations: P
 Terminations: T/H & SMT



SSM / TSM

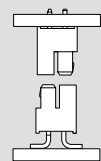
Pitch: 2.54 mm
 Total number of I/Os: 4 - 72
 Stack Height: 11.2 mm
 Orientations: P, PE, H
 Terminations: SMT & MT



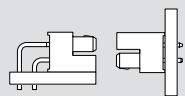
SSW / TSM

Pitch: 2.54 mm
 Total number of I/Os: 4 - 72
 Stack Height: 12.3 mm
 Orientations: P, PE
 Terminations: T/H, SMT & MT

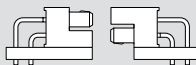
ORIENTATIONS



Parallel (P)

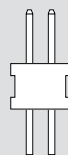


Perpendicular (PE)

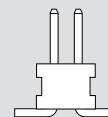


Horizontal (H)

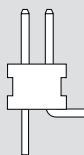
TERMINATIONS



Through-hole (T/H)



Surface Mount (SMT)



Mixed Technology (MT)